



Welcome to **E-XFL.COM** 

What is "Embedded - Microcontrollers"?

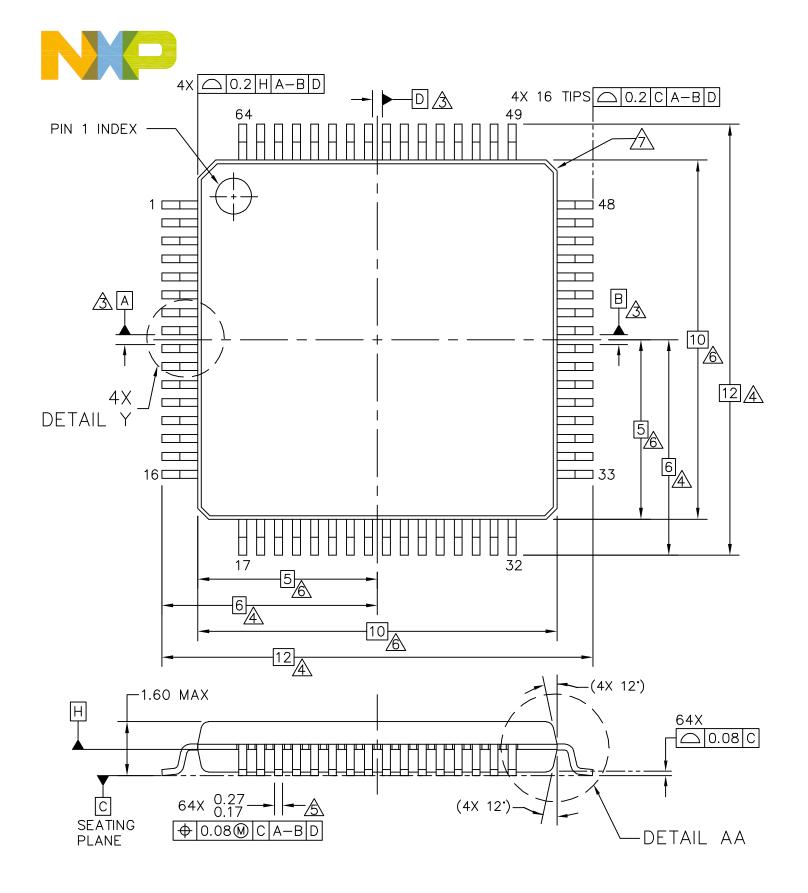
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

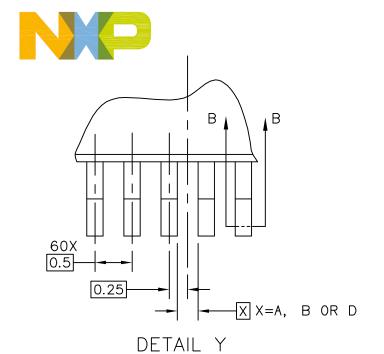
Speed Connectivity	-
Peripherals	-
Number of I/O	-
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	-
Voltage - Supply (Vcc/Vdd)	-
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)

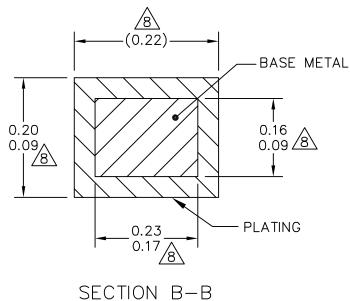
Email: info@E-XFL.COM

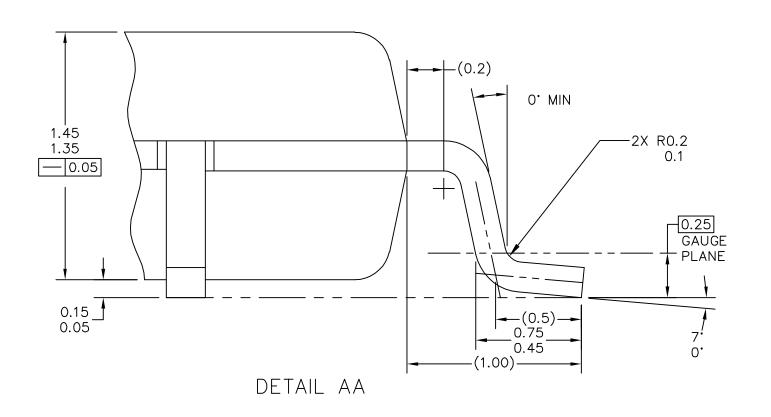
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE		PRINT VERSION NOT	TO SCALE
TITLE:		DOCUMEN	NT NO: 98ASS23234W	REV: G
LQFP, 10 X 10 X 1.4 PKG, 0.5	PITCH 64LD	STANDARD: JEDEC MS-026 BCD		
10 / 10 / 1.1 1 1 (0, 0.0	111011, 0125	S0T1699	9-1 2	5 JAN 2016







NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE:	DOCUMEN	NT NO: 98ASS23234W	REV: G	
LQFP, 10 X 10 X 1.4 PKG, 0.5	PITCH 64LD	STANDARD: JEDEC MS-026 BCD		
	, , , , , , , , , , , , , , , , , , , ,	S0T1699	9–1 25	JAN 2016



## NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3 DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- A DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
- THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 MM.
- THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
- A EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- A THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 MM AND 0.25 MM FROM THE LEAD TIP.

NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OU	TLINE	PRINT VERSION NO	T TO SCALE
TITLE:		DOCUME	NT NO: 98ASS23234W	REV: G
LQFP, 10 X 10 X 1.4 PKG, 0.5	STANDAF	RD: JEDEC MS-026 BC	CD	
10 10 10 11 11 110, 0.0	TITOTI, OTLD	S0T1699	9_1	25 JAN 2016